

N-Channel 100-V (D-S) 175°C MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	r _{DS(on)} (Ω)	_{DS(on)} (Ω) I _D (A)			
100	0.200 @ V _{GS} = 10 V	6.5	2.7		
	$0.225 @ V_{GS} = 4.5 V$	6.0	2.1		





Order Number: SUD06N10-225L SUD06N10-225L—E3 (ILead (Pb)-Free)

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C UNLESS OTHERWISE NOTED)					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	100		
Gate-Source Voltage		V _{GS}	± 20	V	
	$T_{C} = 25^{\circ}C$		6.5		
Continuous Drain Current $(T_J = 175^{\circ}C)^b$	$T_{C} = 125^{\circ}C$	I _D	3.75		
Pulsed Drain Current		I _{DM}	8.0	А	
Continuous Source Current (Diode Conduction)		ا _S	6.5		
Avalanche Current		I _{AR}	5.0		
Repetitive Avalanche Energy (Duty Cycle \leq 1%)	L = 0.1 mH	E _{AR}	1.25	mJ	
	$T_{C} = 25^{\circ}C$	_	20 ^b		
Maximum Power Dissipation	$T_A = 25^{\circ}C$	P _D	1.5 ^a	W	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
	$t \le 10 \text{ sec}$	R _{thJA}	40	50		
Junction-to-Ambient ^a	Steady State		80	100	°C/W	
Junction-to-Case		R _{thJC}	6.0	7.5		

Notes

Surface Mounted on 1" x1" FR4 Board. a.

b. See SOA curve for voltage derating.





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Parameter	Symbol	Test Condition	Min	Тур ^а	Max	Unit	
Static				1			
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I_D = 250 μ A	100			v	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_{D}=250\;\mu\text{A}$	1.0		3.0		
Gate-Body Leakage	I _{GSS}	V_{DS} = 0 V, V_{GS} = ±20 V			±100	nA	
Zero Gate Voltage Drain Current		$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$			1		
	I _{DSS}	V_{DS} = 100 V, V_{GS} = 0 V, T_J = 125 $^\circ C$			50	μA	
		V_{DS} = 100 V, V_{GS} = 0 V, T_J = 175 $^\circ C$			250	1	
On-State Drain Current ^b	I _{D(on)}	$V_{DS} = 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	8.0			Α	
		V_{GS} = 10 V, I _D = 3 A		0.160	0.200		
Desir Osuma Os Otata Dasistanash		V_{GS} = 10 V, I_D = 3 A, T_J = 125 $^\circ C$	0.350				
Drain-Source On-State Resistance ^b	r _{DS(on)}	V_{GS} = 10 V, I_D = 3 A, T_J = 175 $^\circ C$			0.450	Ω	
		V_{GS} = 4.5 V, I_{D} = 1.0 A		0.180	0.225		
Forward Transconductanceb	9 _{fs}	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 3 \text{ A}$		8.5		S	
Dynamic ^a							
Input Capacitance	C _{iss}			240		pF	
Output Capacitance	C _{oss}	V_{GS} = 0 V, V_{DS} = 25 V, F = 1 MHz		42			
Reverse Transfer Capacitance	C _{rss}			17			
Total Gate Charge ^c	Qg			2.7	4.0	nC	
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 50 V, $~V_{GS}$ = 5 V, I_{D} = 6.5 A		0.6			
Gate-Drain Charge ^c	Q _{gd}			0.7			
Turn-On Delay Time ^c	t _{d(on)}			7	11	- ns	
Rise Time ^c	tr	$\begin{array}{l} \text{V}_{\text{DD}} = \text{50 V, R}_{\text{L}} = \text{7.5 }\Omega \\ \text{I}_{\text{D}} \ \cong \ \text{6.5 A, V}_{\text{GEN}} = \text{10 V, R}_{\text{g}} = \text{2.5 }\Omega \end{array}$		8	12		
Turn-Off Delay Time ^c	t _{d(off)}			8	12		
Fall Time ^c	t _f			9	14		
Source-Drain Diode Ratings and	d Characteristi	c (T _C = 25°C)					
Pulsed Current	I _{SM}				8.0	А	
Diode Forward Voltage ^b	V _{SD}	$I_F = 6.5 \text{ A}, V_{GS} = 0 \text{ V}$		0.9	1.3	V	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 6.5 A, di/dt = 100 A/μs		35	60	ns	

Notes

Guaranteed by design, not subject to production testing. Pulse test; pulse width $\leq 300 \ \mu$ s, duty cycle $\leq 2\%$. Independent of operating temperature. a.

b.

c.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



SUD06N10-225L Vishay Siliconix

 $T_C = -55^{\circ}C$

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)





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 $T_J = 25^{\circ}C$

1.0

1.2

Source-Drain Diode Forward Voltage

T_J = 175°C

0.4

0.6

V_{SD} - Source-to-Drain Voltage (V)

0.8

10

1 - 0

0.2

S - Source Current (A)

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)



THERMAL RATINGS



Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?71253.



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